

WHAT IS CLAIMED IS:

1. A power semiconductor module with a connection structure in which an electrode terminal whose one end is connected with an electric power semiconductor device which is resin sealed inside of the case, is exposed along an outer surface of a case for taking out electrode from the semiconductor device, and is electrically connected to an electrode for external connection disposed on the electrode terminal,

10 wherein a female screw hole for screwing is provided on side of the outer surface of the case, a male screw member formed at its opposite ends with screw threads is threadedly engaged with the female screw hole through the electrode terminal.

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2. The power semiconductor module according to claim 1, wherein a nut having the female screw hole is embedded in the outer surface of the case, and the nut is fixed to a lower surface of the electrode terminal.

20 3. The power semiconductor module according to claim 1, wherein said electrode terminal has said female screw hole.

4. The power semiconductor module according to claim 1, wherein said male screw member has different nominal diameters at opposite ends.

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5. The power semiconductor module according to claim 1, wherein said male screw member has threads at opposite ends of which directions are opposite from each other.

6. The power semiconductor module according to claim 1, wherein at least one nut is fixed to a middle portion of said male screw member.

7. The power semiconductor module according to any one of claim 1, wherein a middle portion of said male screw member is formed with a discontinuous portion having no screw thread.

8. The power semiconductor module according to claim 1, wherein said male screw member is threadedly engaged with said female screw hole through a plurality of electrode terminals.